

Silicon Nanotechnology

Ken David

**Director, Components Research
Technology & Manufacturing Group
Intel Corp.**

February 18, 2004



Agenda

What is Nanotechnology?

Nanoscaling

Nonclassical CMOS

Novel Devices

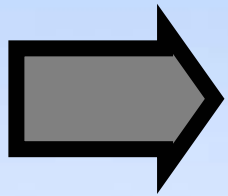
Summary

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Agenda



What is Silicon Nanotechnology?

CMOS Nanoscaling

Nonclassical CMOS

Novel Devices

Summary

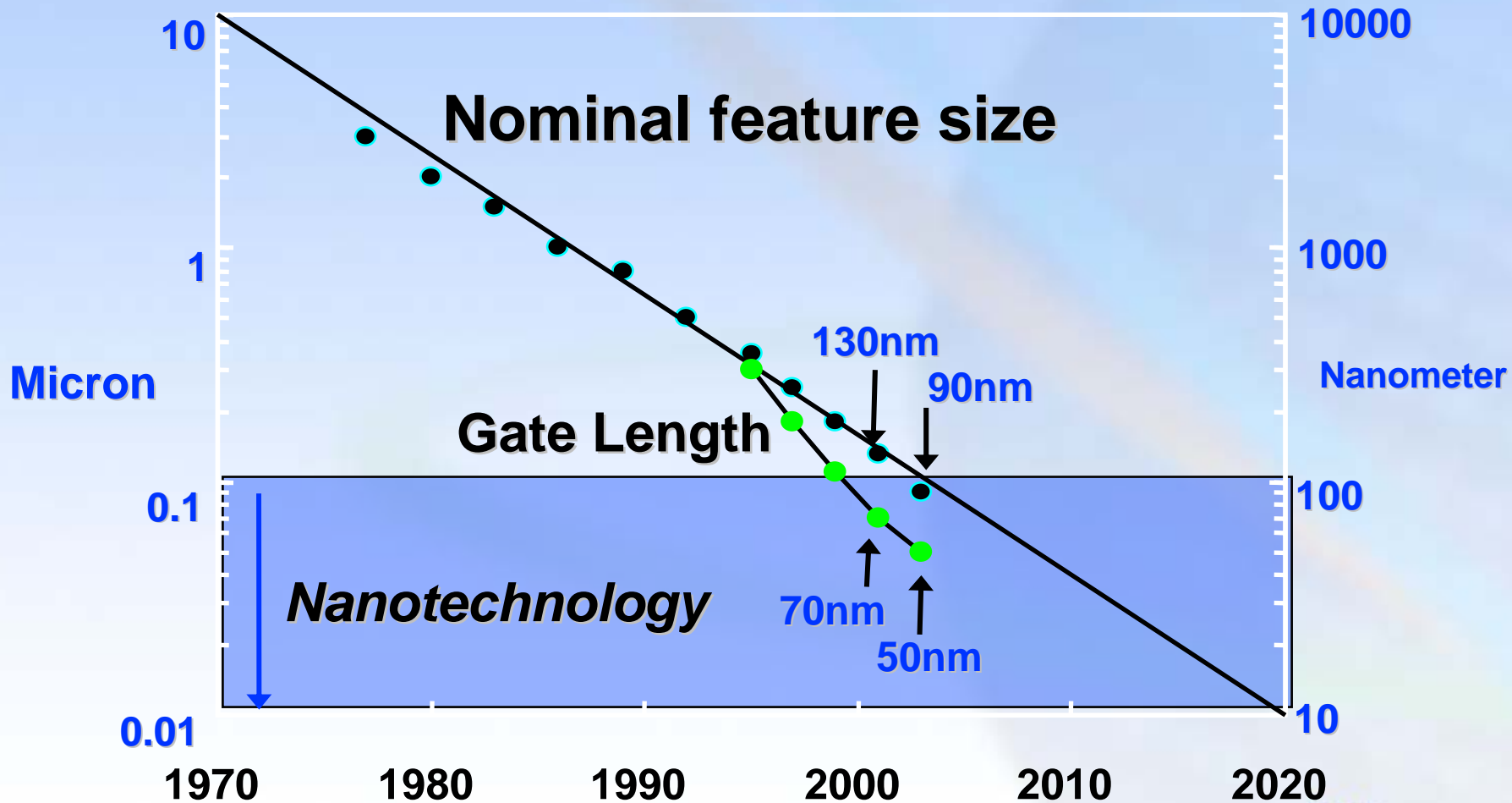
Nanotechnology Definition

“Research and technology development at the atomic, molecular or macromolecular levels, in the length scale of approximately **1 - 100 nanometer** range.”

Dr. Mike Roco, National Science and Technology Council, February 2000

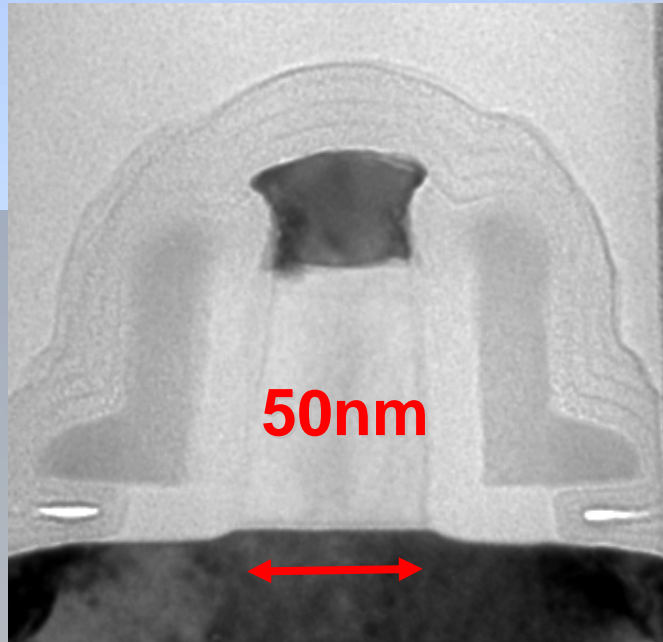
Intel started sub-100nm production in Q3'00

Technology Scaling



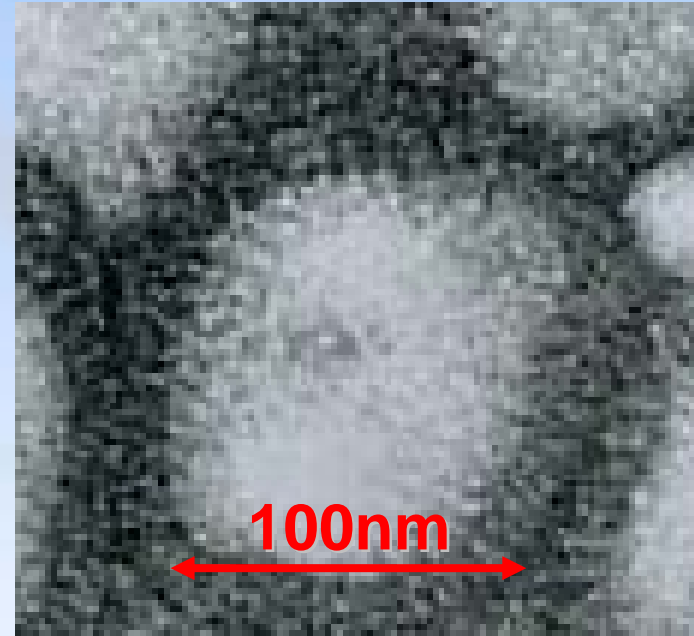
Nanotechnology Today

Example of today's technology: 50 nm transistor dimension



**Transistor for
90nm-node
Gate oxide=1.2nm**

Source: Intel



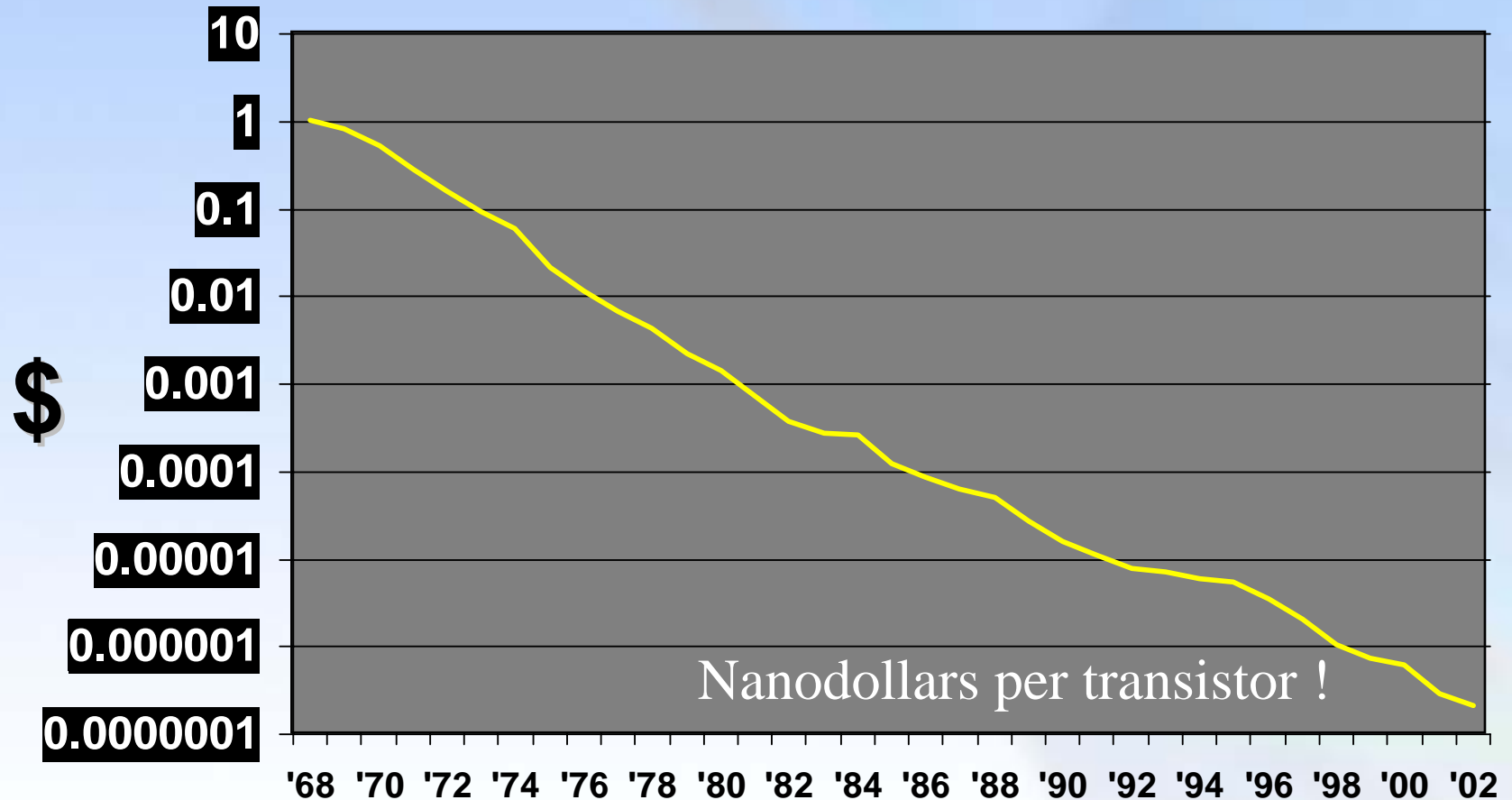
Influenza virus

Source: CDC

**Intel 2003 Silicon Nanotech Product
Revenue >\$20B**

Scaling => Nanoscaling

Nearly 7 Orders Of Magnitude Reduction in Cost/Transistor

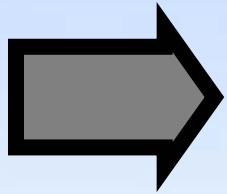


Source: WSTS/Dataquest/Intel, 8/02

Silicon Nanotechnology Evolution

- **Continued CMOS Nanoscaling**
 - materials, lithography innovation
- **Implement Non-classical CMOS**
 - new architectures, new structures
- **Transition to Novel devices**
 - alternative state variables
 - must meet device requirements and demonstrate integrability

Agenda



What is Silicon Nanotechnology?

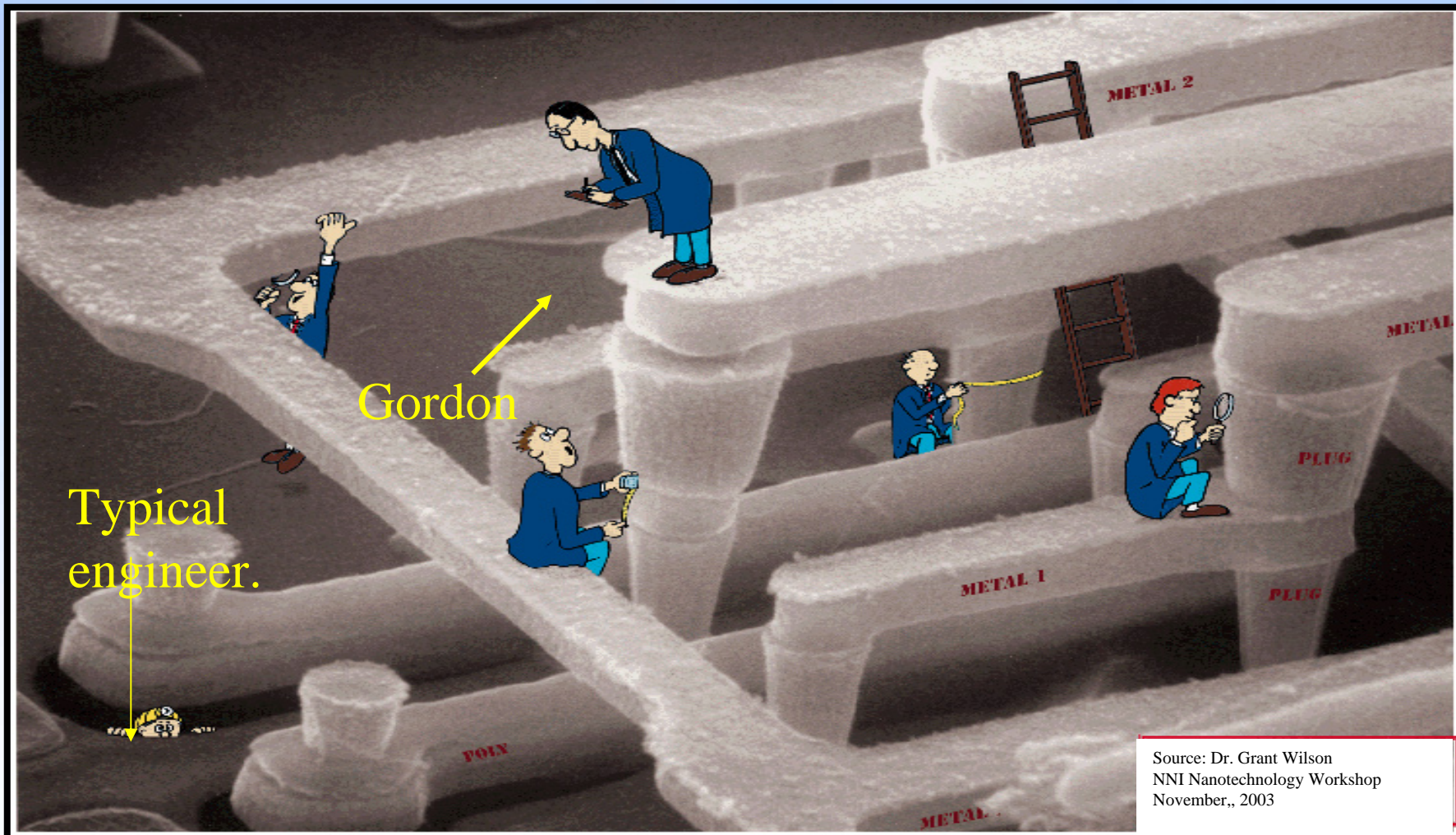
CMOS Nanoscaling

Nonclassical CMOS

Novel Devices

Summary

CMOS Nanoscaling....Extending Moore's Law



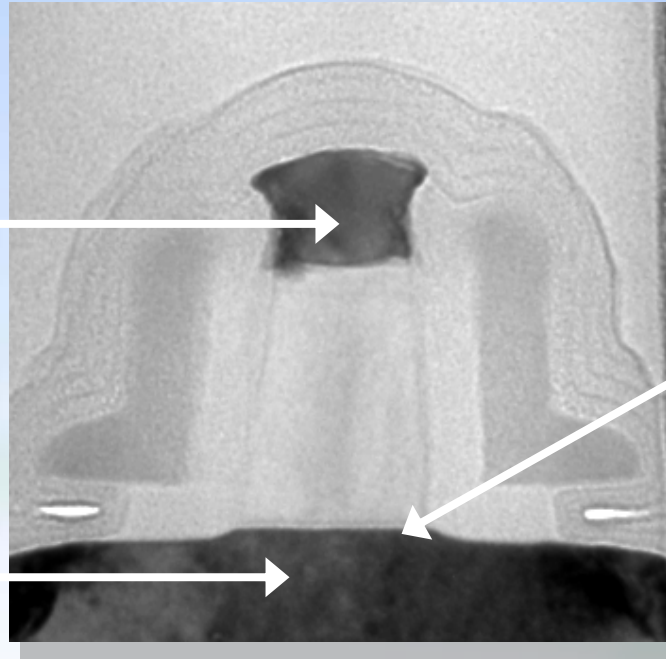
Source: Dr. Grant Wilson
NNI Nanotechnology Workshop
November, 2003

New Materials, Devices Extend Si Scaling

Changes Made

Gate
Silicide added

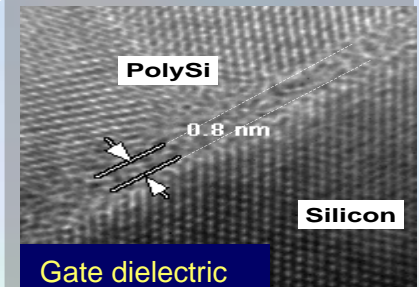
Channel
Strained silicon



Transistor

Future Options

High-k gate dielectric



Gate dielectric less than 3 atomic layers thick

Source: Intel

New Materials, Devices Extend Si Scaling

Changes Made

Metal lines

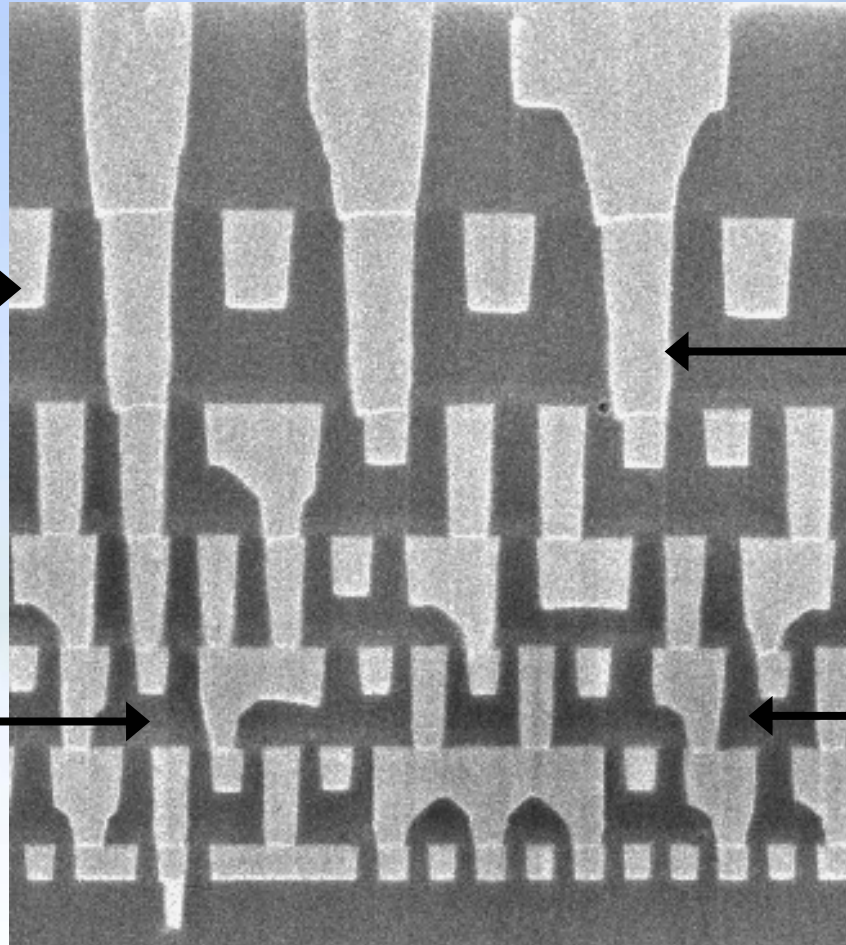
Al → Cu

Insulating dielectric

SiO₂ → SiOF

→ CDO

(low-k)



Future Options

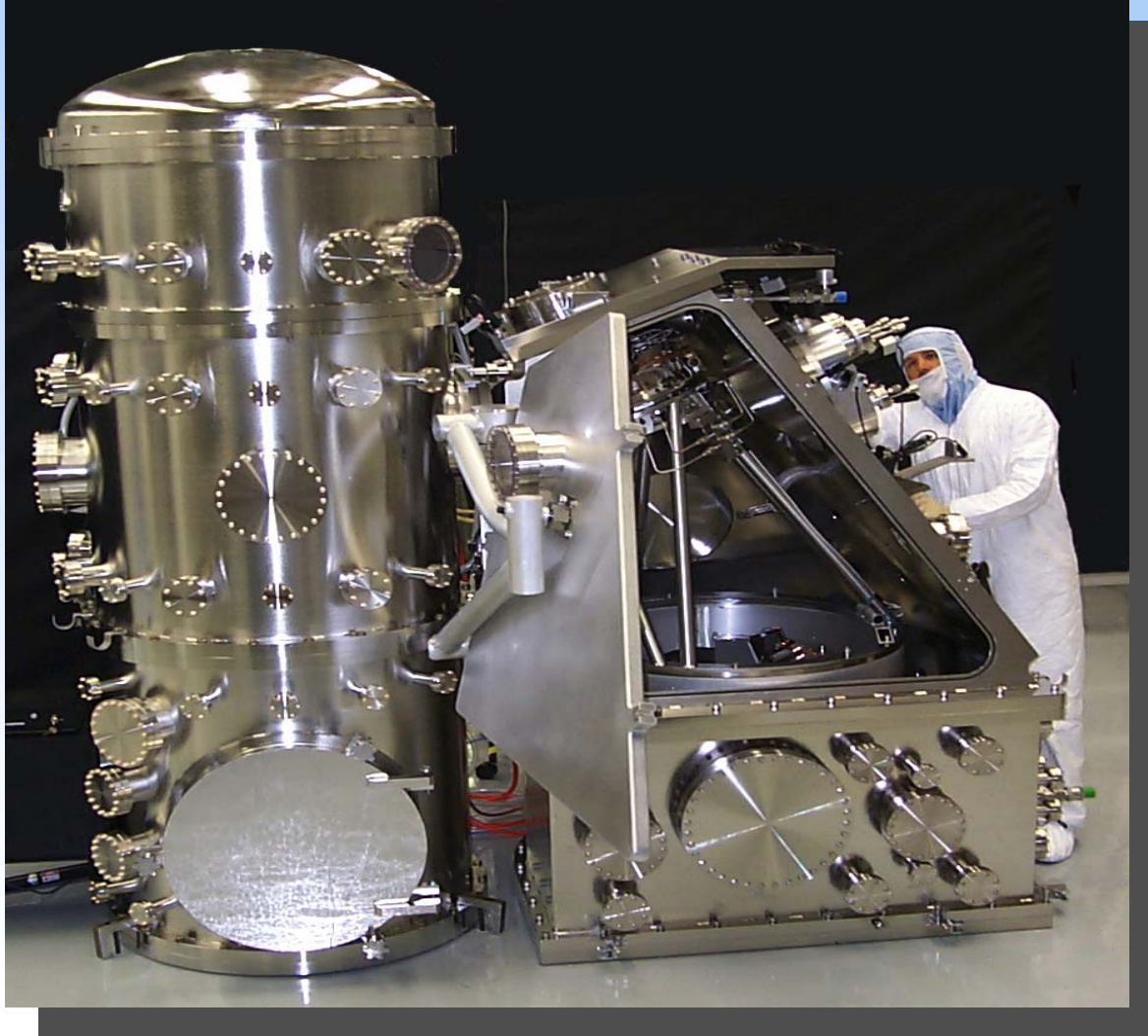
New
Thinner
Barrier
Layers

Ultra
Low-k
Dielectric

Interconnects

Source: Intel

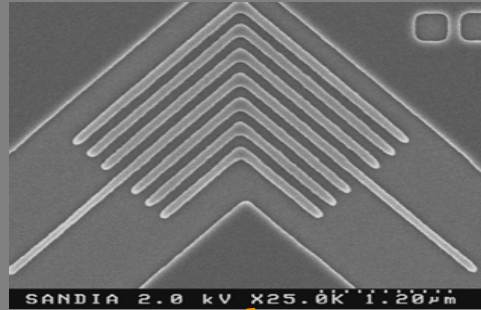
EUV LLC Consortium Demonstrates EUVL with Prototype Exposure Tool



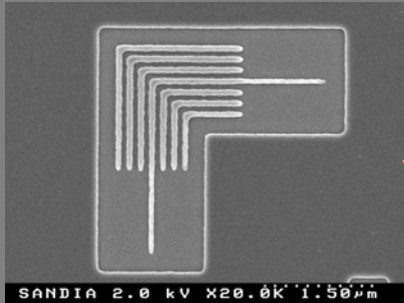
EUV Lithography - Full Field ETS Images

(using 0.1 NA system)

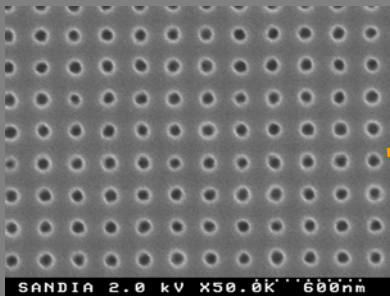
100 nm Elbows 1:1



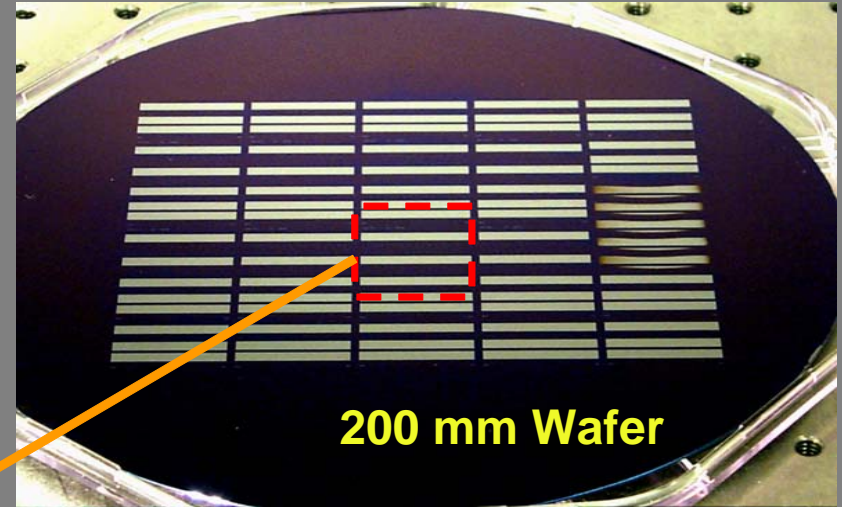
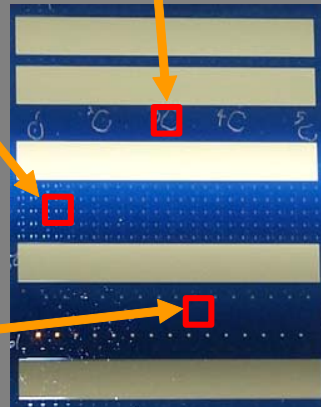
80 nm Elbows 1:1



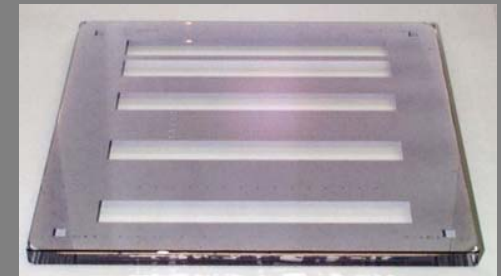
100 nm contacts 1:1



24 x 32.5 mm² field



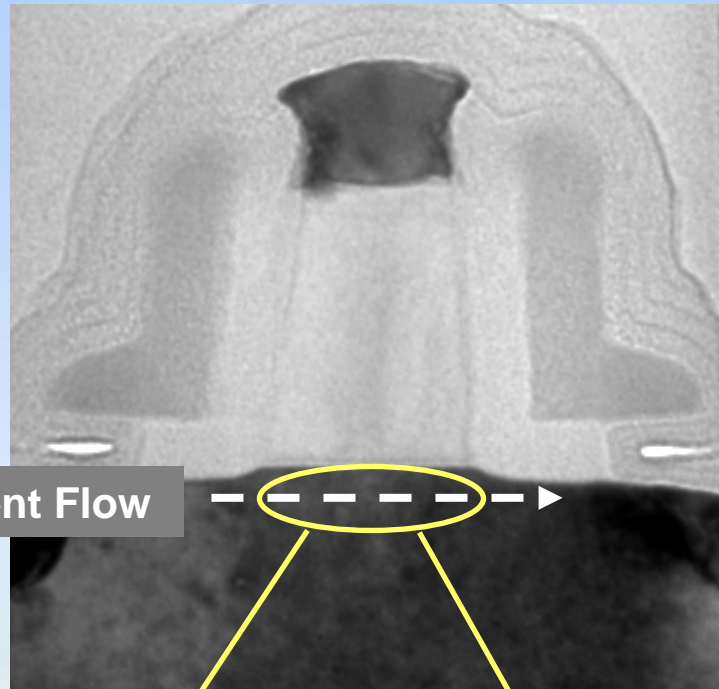
4x5 matrix



152 mm², 4X
Reflective Mask

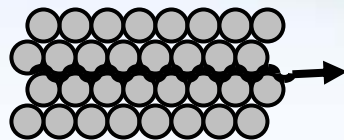
Printing 80 nm images at 0.1 NA is equivalent to printing 32 nm with 0.25 NA production system

Strained Silicon Transistors

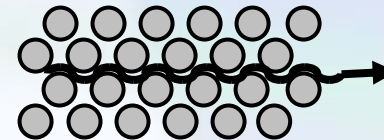


Current Flow

Normal
electron
flow



Normal Silicon Lattice



Strained Silicon Lattice

Faster
electron
flow

Strained Silicon Transistors

Strained silicon benefits

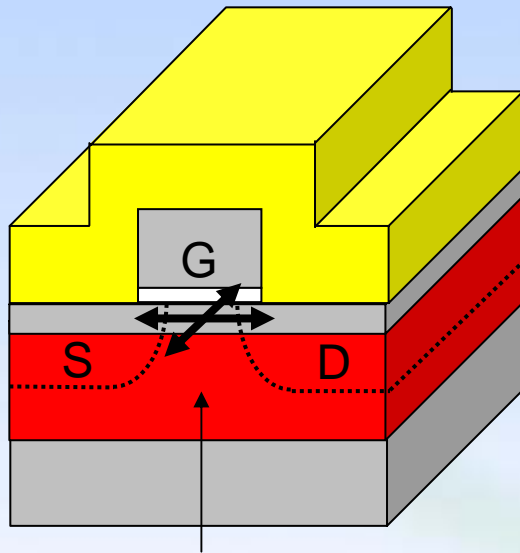
- Strained silicon lattice increases electron and hole mobility in transistor channels
- Greater mobility results in 10-20% increase in transistor current flow (drive current)
- Increased drive current = increased transistor performance
- Both NMOS and PMOS transistor performance improved

Strained silicon process

- Intel's strained silicon process is unique in the industry
- No detriments to transistor short channel behavior or junction leakage
- The added process steps increase total processing cost by only ~2%

Transistor Strain Techniques

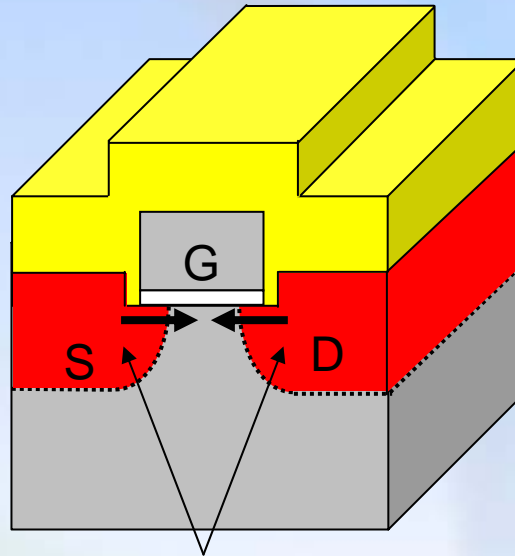
Traditional Approach



Graded SiGe Layer

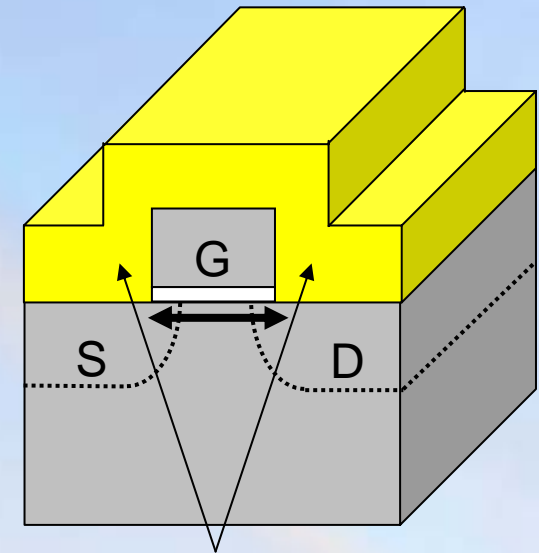
Biaxial
Tensile Strain

Intel's 90nm Technology



Selective SiGe S-D

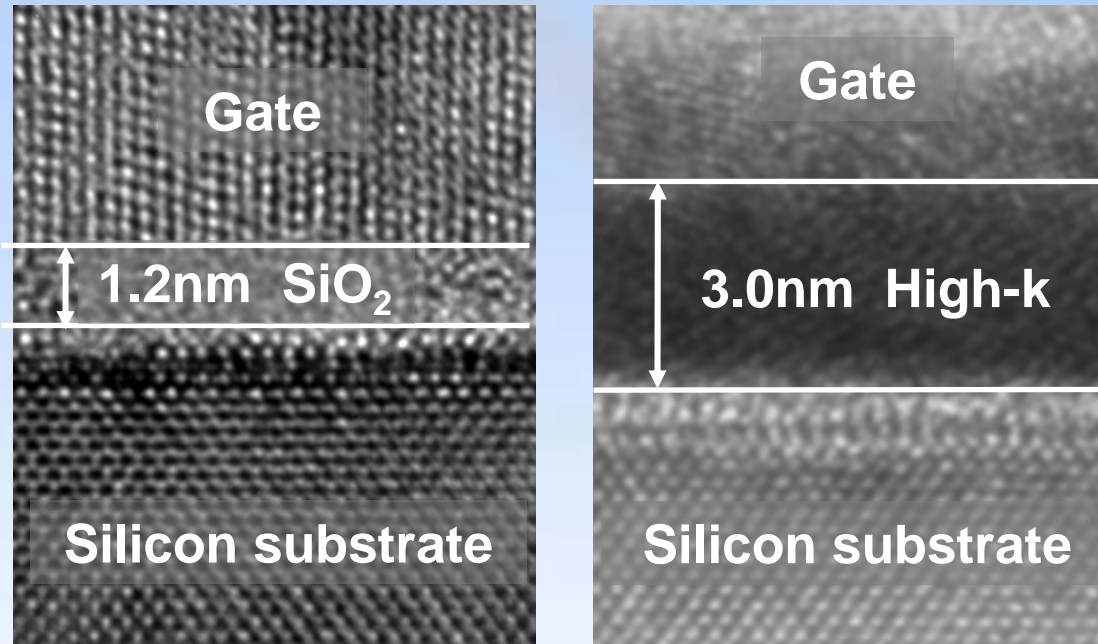
Uniaxial
Compressive Strain
for PMOS



Tensile Si₃N₄ Cap

Uniaxial
Tensile Strain
for NMOS

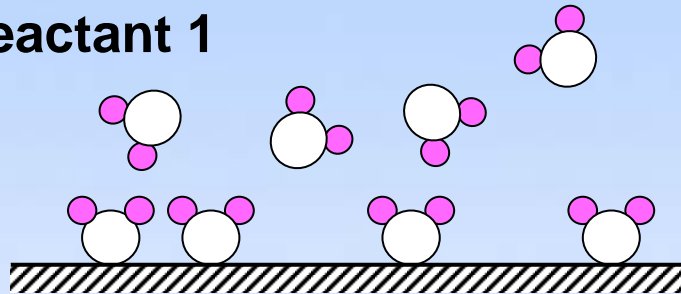
High-K Gate Dielectric



	<u>90nm process</u>	<u>High-k</u>
Capacitance:	1.0x	1.6x
Leakage:	1.0x	< 0.01x

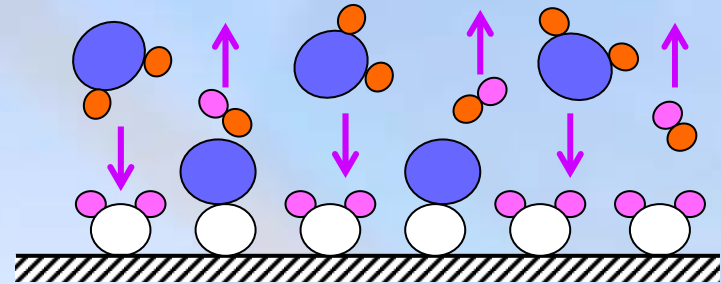
High-K Gate Dielectric Formed Using Atomic Layer Chemical Vapor Deposition

Reactant 1



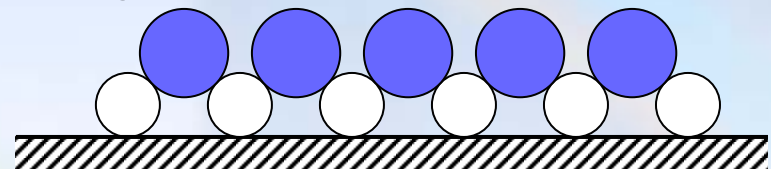
Step 1

Introduce reactant 2

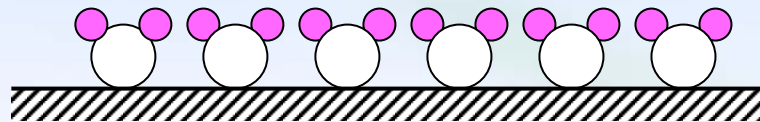


Step 3

Final film



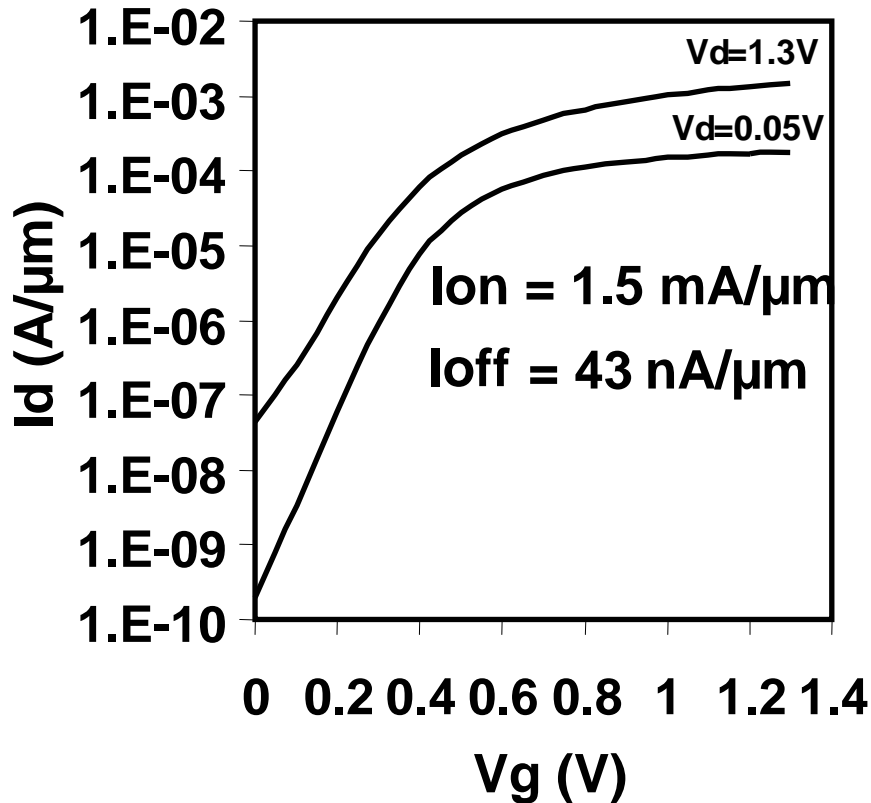
Step 4



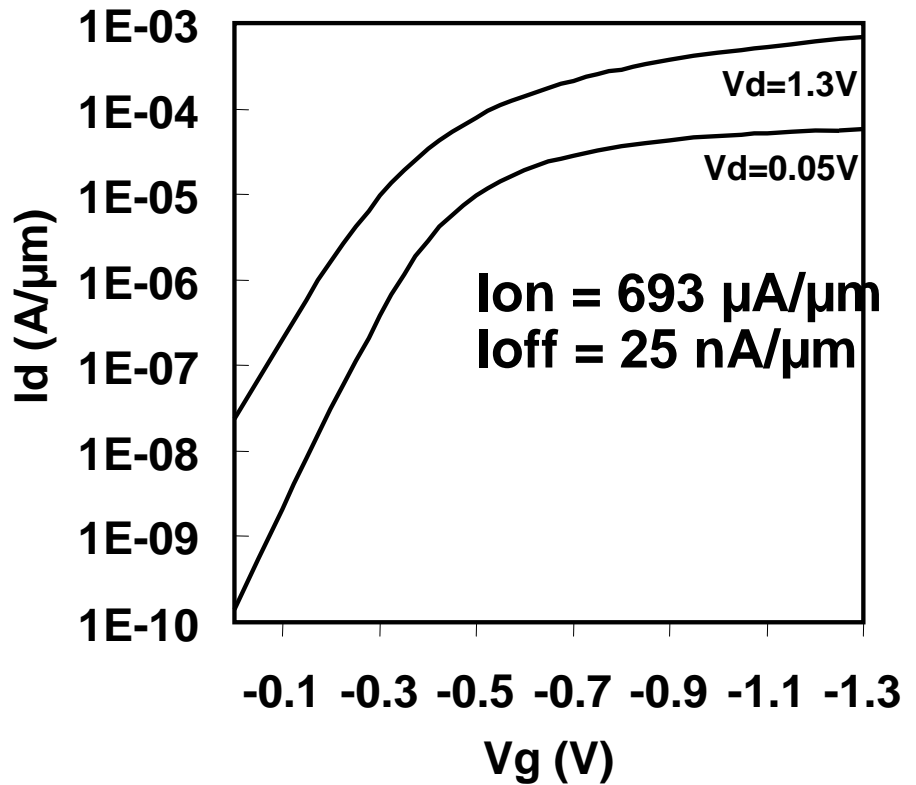
Step 2

- “Self-assembly process” ready for manufacturing
- Sequential introduction of precursors molecules
- Allows for precise building of the dielectric film

High-K/Metal-Gate Achieved Recording-Setting Performance



NMOS Transistor



PMOS Transistor

Continuation of Moore's Law

Process Name	P856	P858	Px60	P1262	P1264	P1266	P1268	P1270
1st Production	1997	1999	2001	2003	2005	2007	2009	2011
Process Generation	0.25 μ m	0.18 μ m	0.13 μ m	90 nm	65 nm	45 nm	32 nm	22 nm
Wafer Size (mm)	200	200	200/300	300	300	300	300	300
Inter-connect	Al	Al	Cu	Cu	Cu	Cu	Cu	?
Channel	Si	Si	Si	Strained Si	Strained Si	Strained Si	Strained Si	Strained Si
Gate dielectric	SiO ₂	SiO ₂	SiO ₂	SiO ₂	SiO ₂	High-k	High-k	High-k
Gate electrode	Poly-silicon	Poly-silicon	Poly-silicon	Poly-silicon	Poly-silicon	Metal	Metal	Metal

Source: Intel

Introduction targeted at this time

Subject to change

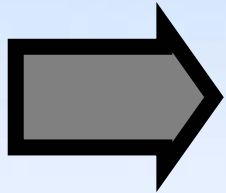
Intel found a solution for High-k and metal gate



Agenda

What is Silicon Nanotechnology?

Nanoscaling

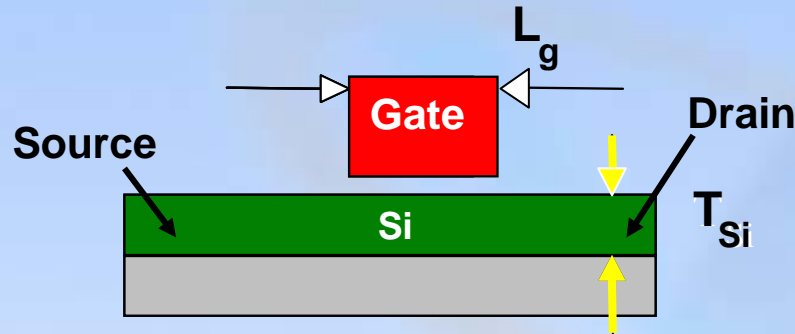


Nonclassical CMOS

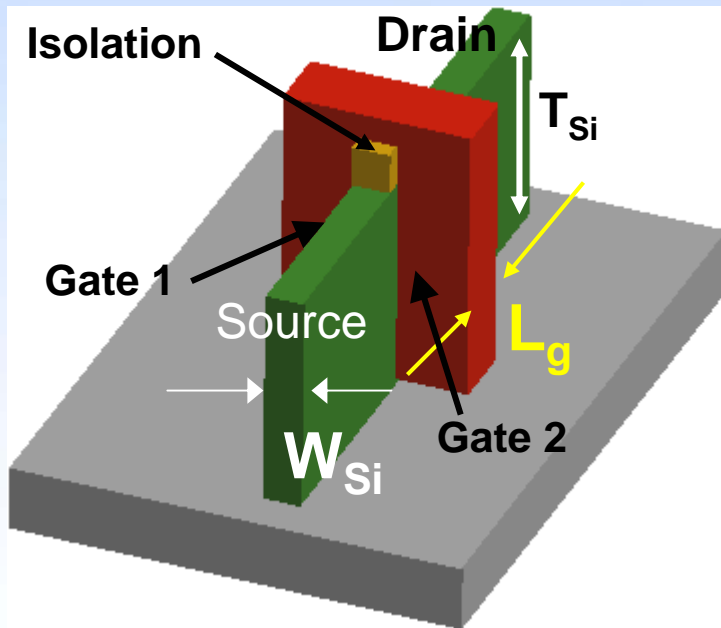
Novel Devices

Summary

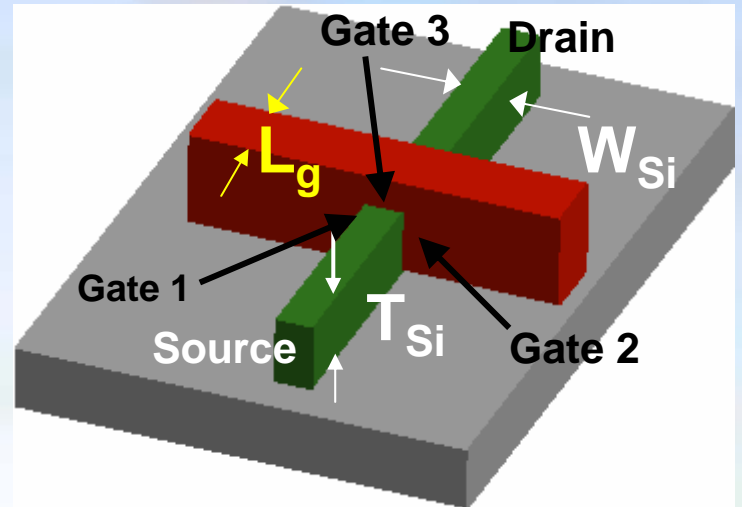
Transistor Architectures



(Planar)



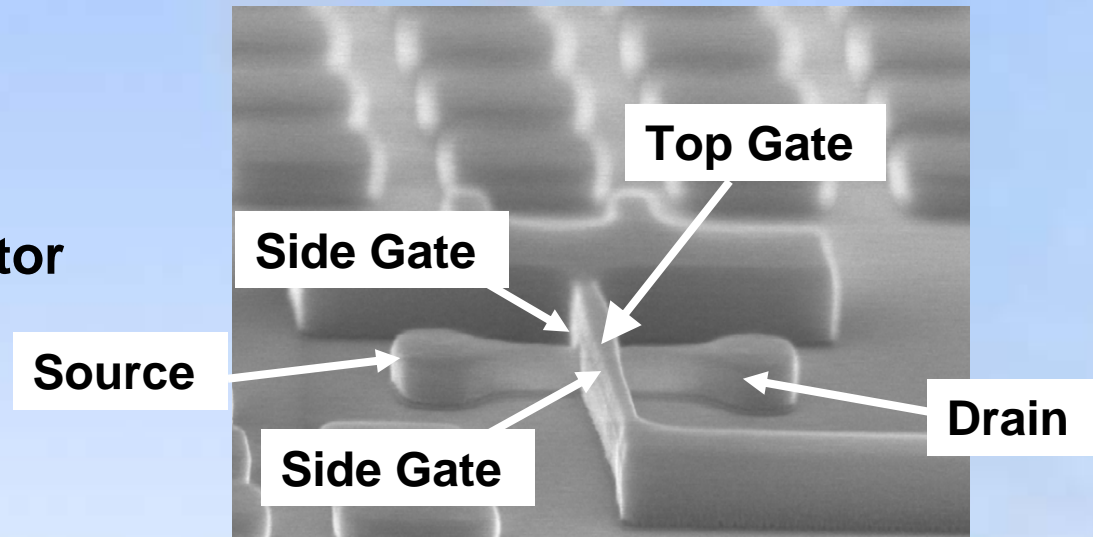
Double-gate (e.g. FINFET)
(Non-Planar)



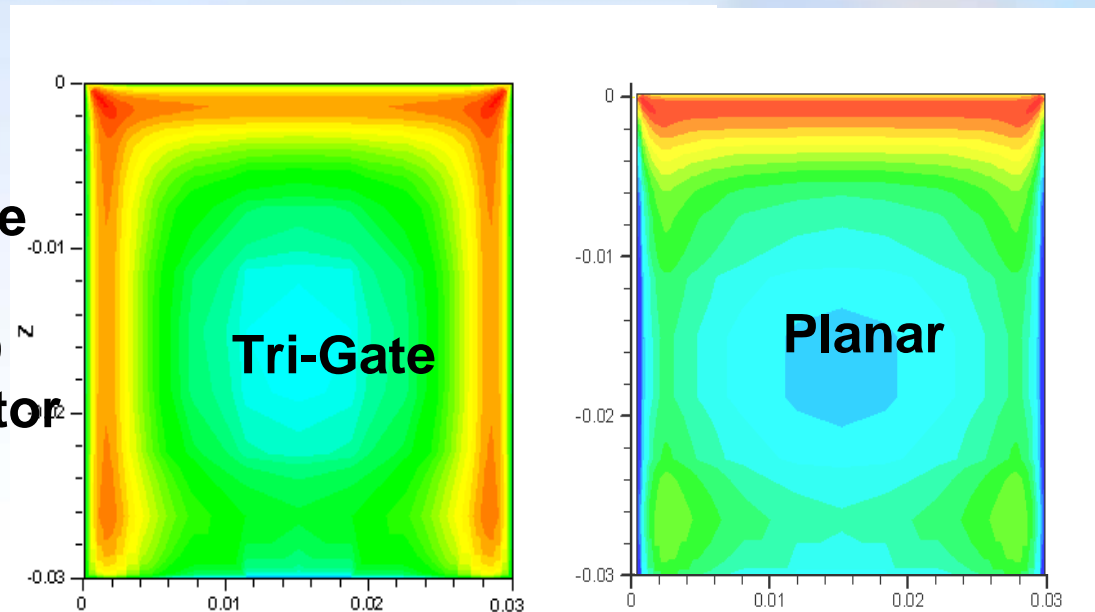
Tri-gate
(Non-Planar)

Tri-Gate Transistor

Actual photo
30nm tri-gate transistor



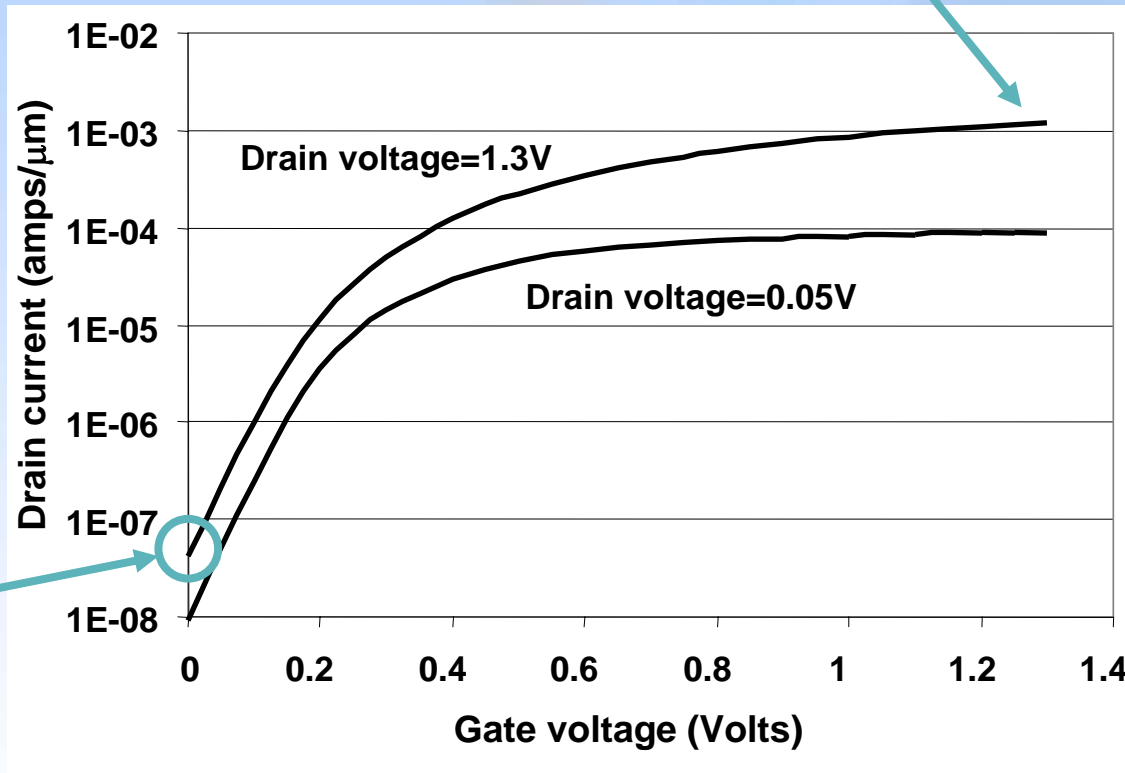
Simulation
Cross-section of silicon channel shows much more current flow (indicated by red) in tri-gate transistor than in planar transistor



Source: Intel

World Record Non-Planar Performance

Very high drive current at saturation, 1.23 mA/ μm



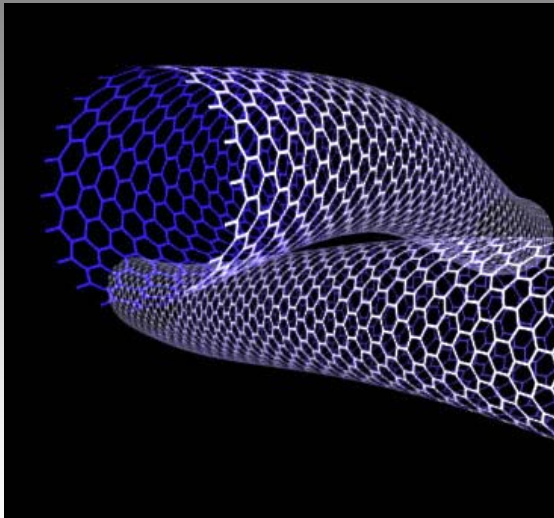
Very low leakage, 40nA/ μm

Tri-gate transistor exhibits excellent device characteristics

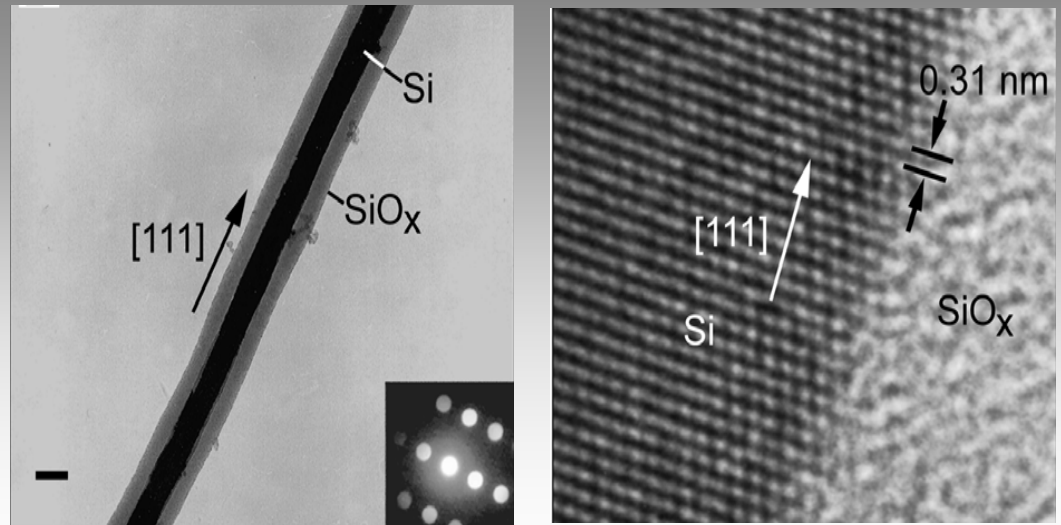
Non-Classical CMOS

- Many options including nanotubes/nanowires
- Collaborations with universities in progress

Carbon Nanotube



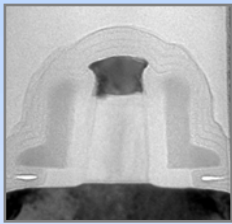
Silicon Nanowire



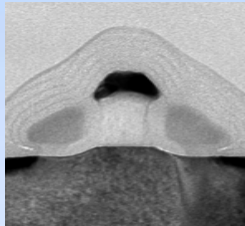
Source: Morales & Lieber, Science **279**, 208 (1998)

CMOS Device Scaling Demonstration

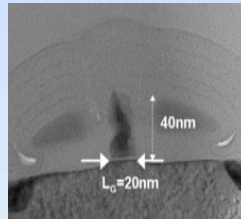
90nm Node
2003



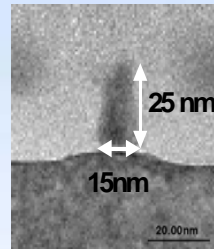
65nm Node
2005



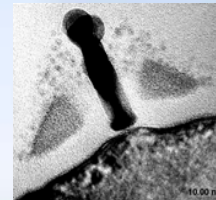
45nm Node
2007



32nm Node
2009

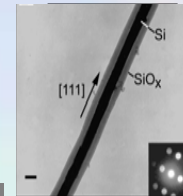


22nm Node
2011



16 nm node
2013

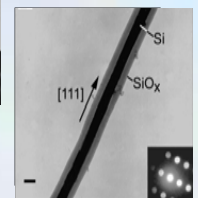
11nm node
2015



TBD

Si nanowires?!

8 nm node
2017



TBD

50nm Length
(IEDM2002)

30nm
Prototype
(IEDM2000)

20nm Prototype
(VLSI2001)

15nm Prototype
(IEDM2001)

10nm Prototype
(DRC 2003)

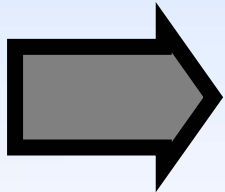
Integration of nanotubes, nanowires onto Si by end of this decade will extend device scaling well into next decade

Agenda

What is silicon Nanotechnology?

Nano Scaling

Non classical CMOS



Novel Devices

Summary

Novel Devices

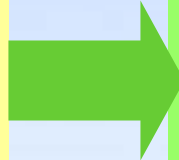
- **Many device options....**
- **Compatibility with CMOS for evolutionary introduction**
- **Directed or self assembly of arrays???**
 - Defect density or purity required....
- **Self correcting architectures??**
- **Nanotechnology needs a richer suite of functionality...**

Collaboration between industry, universities, and government is essential

Novel Devices

What are we looking for?

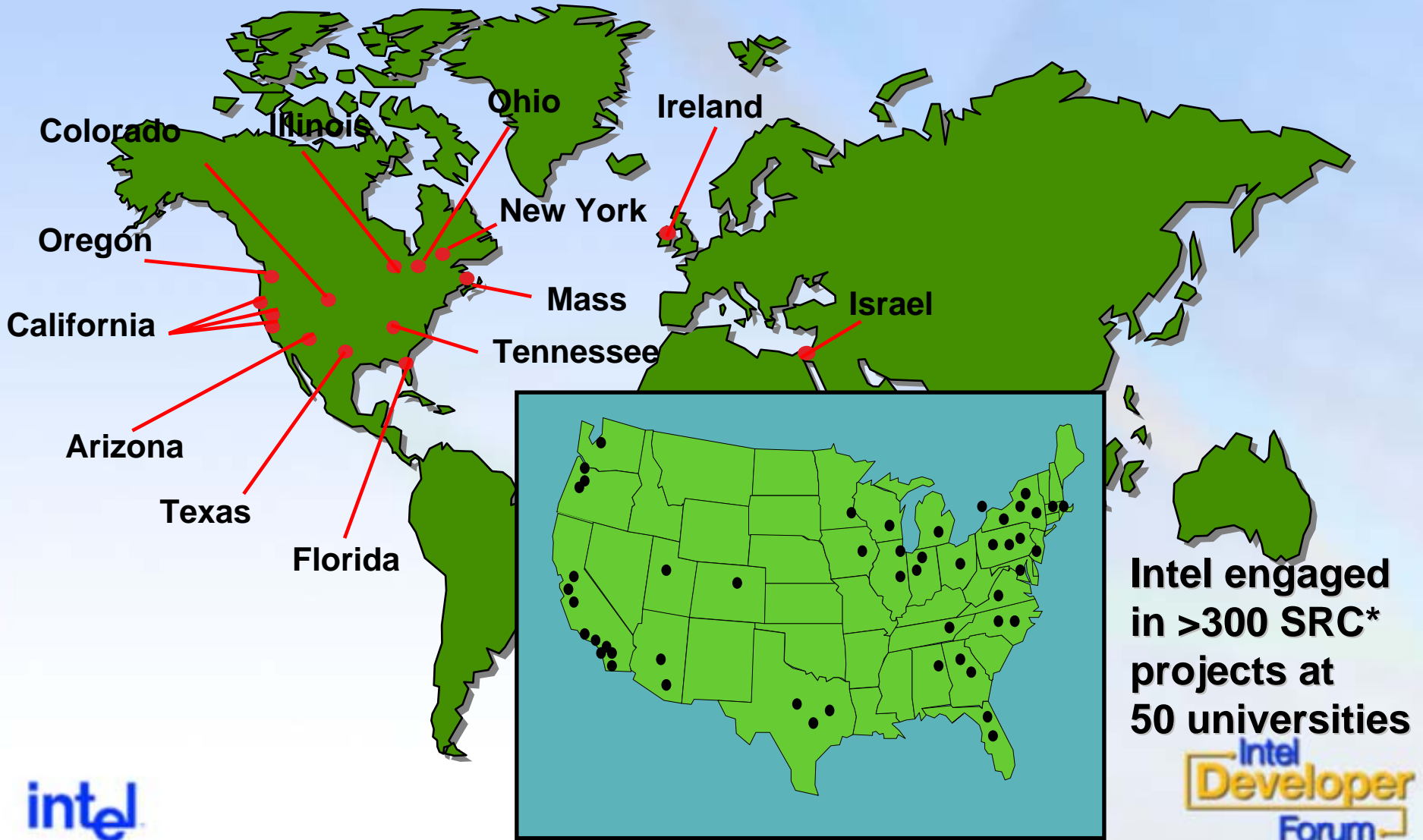
- Required characteristics:
 - Scalability
 - Performance
 - Energy efficiency
 - Gain
 - Operational reliability
 - Room temp. operation
- Preferred approach:
 - CMOS process compatibility
 - CMOS architectural compatibility



- ### Alternative state variables
- **Spin–electron, nuclear, photon**
 - **Phase**
 - **Quantum state**
 - **Magnetic flux quanta**
 - **Mechanical deformation**
 - **Dipole orientation**
 - **Molecular state**

Intel Involved in University Research

Intel-supported Nanotechnology Research at Universities



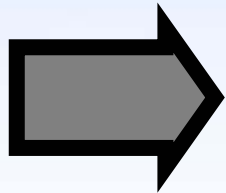
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Summary

Summary

- **Nanotechnology is here today in “state of the art” high speed Si CMOS process technologies**
- **Si nanotechnology process scaling/convergence will continue indefinitely.**
- **New architectures will further extend silicon scaling.**
- **Novel technologies being investigated and may be integrated with silicon technology mid-next decade**
- **Compatibility with CMOS (product development spectrum) will leverage existing learning and enable earlier production of novel devices**

**Please fill out the Session
Evaluation Form.**

Thank You!

The background features a large, semi-transparent image of a microchip die on the right side. Overlaid on this are several glowing, curved lines in shades of blue, orange, and green, suggesting motion or data flow. The text 'Intel Developer Forum' is centered in the upper half of the image. 'Intel' is in blue, 'Developer' is in yellow, and 'Forum' is in blue. A yellow bracket-like graphic surrounds the text.

Intel
Developer
Forum